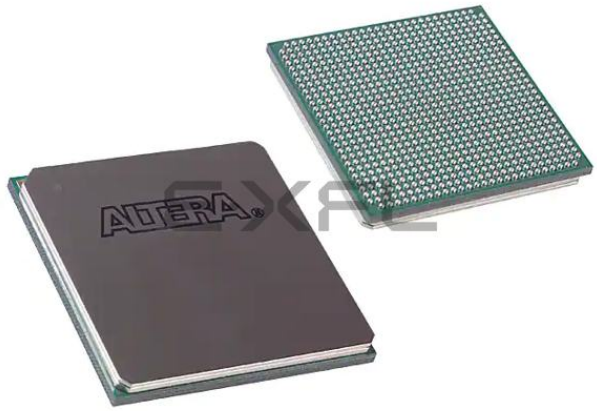


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1694
Number of Logic Elements/Cells	33880
Total RAM Bits	1369728
Number of I/O	361
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	780-BBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2sgx30df780i4n

capable of built-in self test (BIST) generation and verification. The ALT2GXB megafunction in the Quartus II software provides a step-by-step menu selection to configure the transceiver.

Figure 2–1 shows the block diagram for the Stratix II GX transceiver channel. Stratix II GX transceivers provide PCS and PMA implementations for all supported protocols. The PCS portion of the transceiver consists of the word aligner, lane deskew FIFO buffer, rate matcher FIFO buffer, 8B/10B encoder and decoder, byte serializer and deserializer, byte ordering, and phase compensation FIFO buffers.

Each Stratix II GX transceiver channel is also capable of BIST generation and verification in addition to various loopback modes. The PMA portion of the transceiver consists of the serializer and deserializer, the CRU, and the high-speed differential transceiver buffers that contain pre-emphasis, programmable on-chip termination (OCT), programmable voltage output differential (V_{OD}), and equalization.

Transmitter Path

This section describes the data path through the Stratix II GX transmitter. The Stratix II GX transmitter contains the following modules:

- Transmitter PLLs
- Access to one of two PLLs
- Transmitter logic array interface
- Transmitter phase compensation FIFO buffer
- Byte serializer
- 8B/10B encoder
- Serializer (parallel-to-serial converter)
- Transmitter differential output buffer

Transmitter PLLs

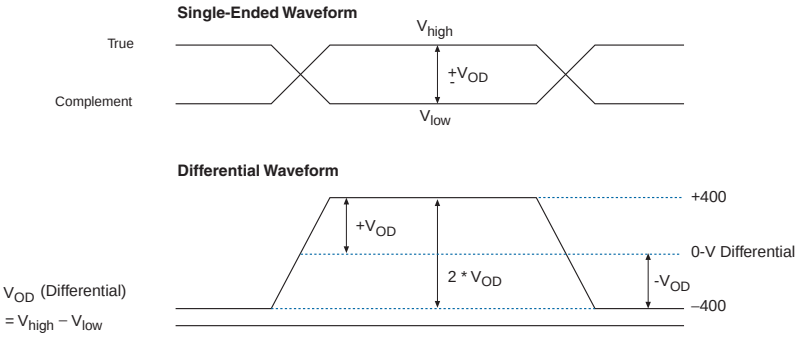
Each transceiver block has two transmitter PLLs which receive two reference clocks to generate timing and the following clocks:

- High-speed clock used by the serializer to transmit the high-speed differential transmitter data
- Low-speed clock to load the parallel transmitter data of the serializer

The serializer uses high-speed clocks to transmit data. The serializer is also referred to as parallel in serial out (PISO). The high-speed clock is fed to the local clock generation buffer. The local clock generation buffers divide the high-speed clock on the transmitter to a desired frequency on a per-channel basis. Figure 2–3 is a block diagram of the transmitter clocks.

Differential signaling conventions are shown in Figure 2–9. The differential amplitude represents the value of the voltage between the true and complement signals. Peak-to-peak differential voltage is defined as $2 \times (V_{HIGH} - V_{LOW}) = 2 \times$ single-ended voltage swing. The common mode voltage is the average of V_{high} and V_{low}.

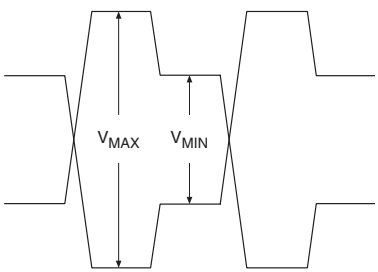
Figure 2–9. Differential Signaling



Programmable Pre-Emphasis

The programmable pre-emphasis module controls the output driver to boost the high frequency components, and compensate for losses in the transmission medium, as shown in Figure 2–10. The pre-emphasis is set statically using the ALT2GXB megafunction or dynamically through the dynamic reconfiguration controller.

Figure 2–10. Pre-Emphasis Signaling



$$\text{Pre-Emphasis \%} = \left(\frac{V_{MAX}}{V_{MIN}} - 1 \right) \times 100$$

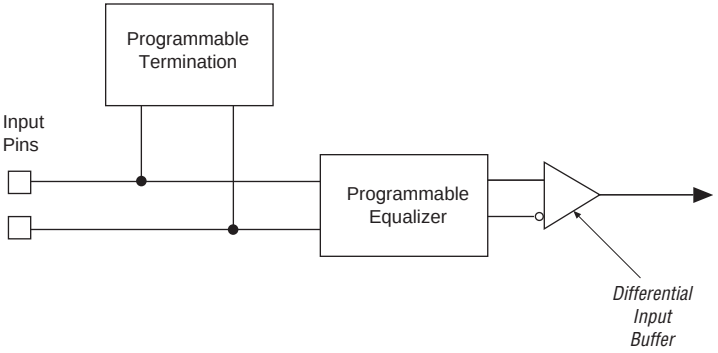
- Lane deskew
- Rate matcher
- 8B/10B decoder
- Byte deserializer
- Byte ordering
- Receiver phase compensation FIFO buffer

Receiver Input Buffer

The Stratix II GX receiver input buffer supports the 1.2-V and 1.5-V PCML I/O standard at rates up to 6.375 Gbps. The common mode voltage of the receiver input buffer is programmable between 0.85 V and 1.2 V. You must select the 0.85 V common mode voltage for AC- and DC-coupled PCML links and the 1.2 V common mode voltage for DC-coupled LVDS links.

The receiver has programmable on-chip 100-, 120-, or 150-Ω differential termination for different protocols, as shown in Figure 2–12. The receiver's internal termination can be disabled if external terminations and biasing are provided. The receiver and transmitter differential termination resistances can be set independently of each other.

Figure 2–12. Receiver Input Buffer



Programmable Termination

The programmable termination can be statically set in the Quartus II software. Figure 2–13 shows the setup for programmable receiver termination. The termination can be disabled if external termination is provided.

The rx_syncstatus signal is not available in bit-slipping mode.

Channel Aligner

The channel aligner is available only in XAUI mode and aligns the signals of all four channels within a transceiver. The channel aligner follows the IEEE 802.3ae, clause 48 specification for channel bonding.

The channel aligner is a 16-word FIFO buffer with a state machine controlling the channel bonding process. The state machine looks for an /A/ (/K28.3/) in each channel, and aligns all the /A/ code groups in the transceiver. When four columns of /A/ (denoted by //A//) are detected, the rx_channelaligned signal goes high, signifying that all the channels in the transceiver have been aligned. The reception of four consecutive misaligned /A/ code groups restarts the channel alignment sequence and sends the rx_channelaligned signal low.

Figure 2–19 shows misaligned channels before the channel aligner and the aligned channels after the channel aligner.

Figure 2–19. Before and After the Channel Aligner

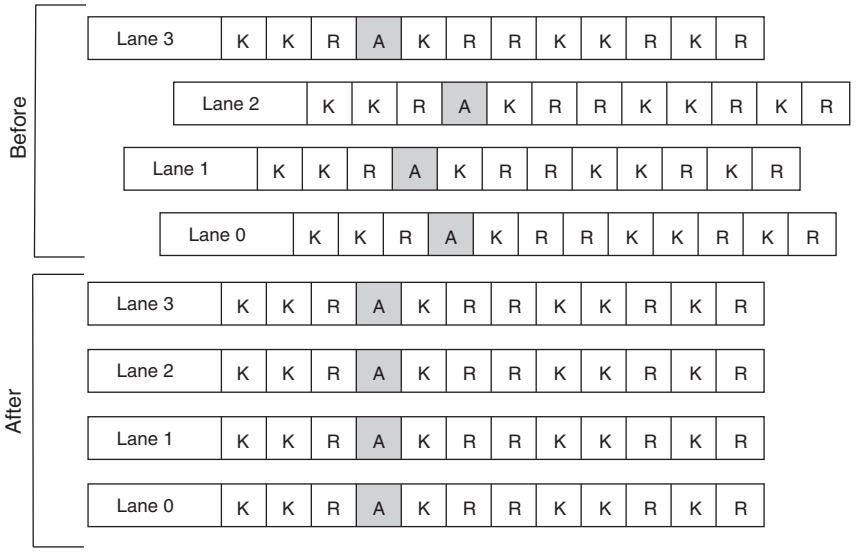
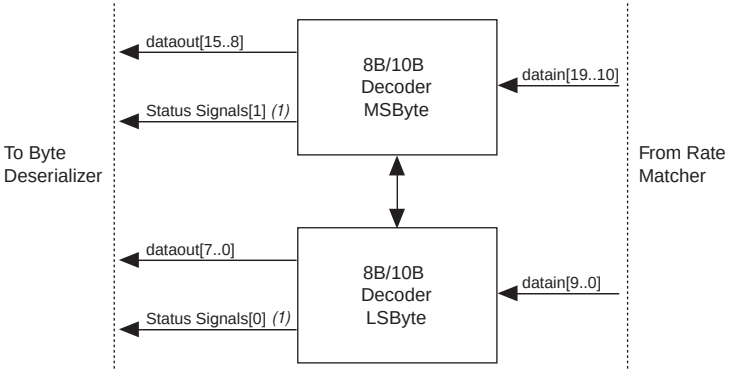
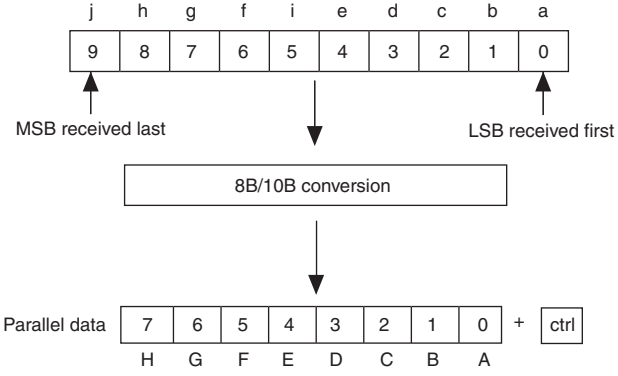


Figure 2–21. 8B/10B Decoder



The 8B/10B decoder in single-width mode translates the 10-bit encoded data into the 8-bit equivalent data or control code. The 10-bit code received must be from the supported Dx.y or Kx.y list with the proper disparity or error flags asserted. All 8B/10B control signals, such as disparity error or control detect, are pipelined with the data and edge-aligned with the data. Figure 2–22 shows how the 10-bit symbol is decoded in the 8-bit data + 1-bit control indicator.

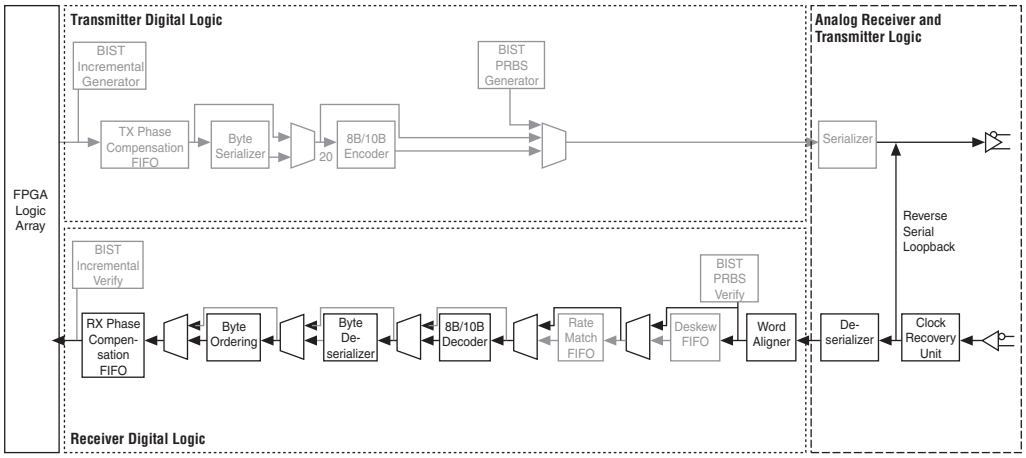
Figure 2–22. 8B/10B Decoder Conversion



The 8B/10B decoder in double-width mode translates the 20-bit (2 × 10-bits) encoded code into the 16-bit (2 × 8-bits) equivalent data or control code. The 20-bit upper and lower symbols received must be from the supported Dx.y or Kx.y list with the proper disparity or error flags

Figure 2–26 shows the data path in reverse serial loopback mode.

Figure 2–26. Stratix II GX Block in Reverse Serial Loopback Mode

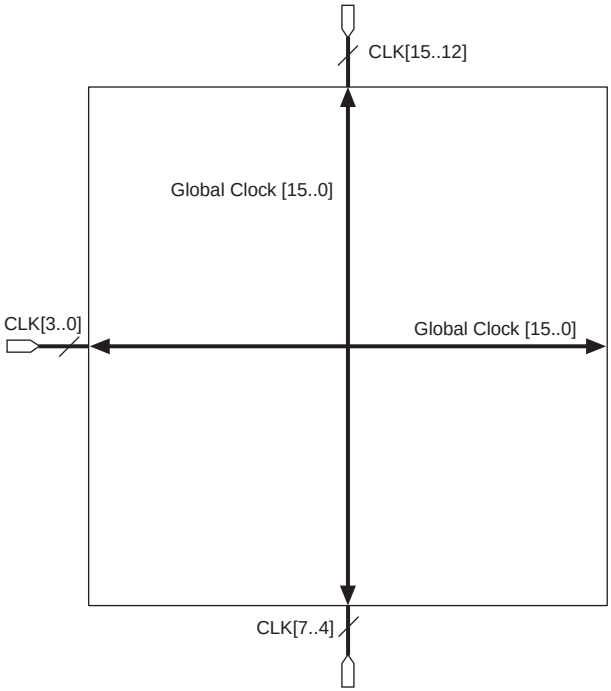


Reverse Serial Pre-CDR Loopback

The reverse serial pre-CDR loopback mode uses the analog portion of the transceiver. An external source (pattern generator or transceiver) generates the source data. The high-speed serial source data arrives at the high-speed differential receiver input buffer, loops back before the CRU unit, and is transmitted though the high-speed differential transmitter output buffer. It is for test or verification use only to verify the signal being received after the gain and equalization improvements of the input buffer. The signal at the output is not exactly what is received since the signal goes through the output buffer and the VOD is changed to the VOD setting level. The pre-emphasis settings have no effect.

generated global clocks and asynchronous clears, clock enables, or other control signals with large fanout. Figure 2–61 shows the 12 dedicated CLK pins driving global clock networks.

Figure 2–61. Global Clocking



Regional Clock Network

There are eight regional clock networks (RCLK[7..0]) in each quadrant of the Stratix II GX device that are driven by the dedicated CLK[15..12] and CLK[7..0] input pins, by PLL outputs, or by internal logic. The regional clock networks provide the lowest clock delay and skew for logic contained in a single quadrant. The CLK pins symmetrically drive the RCLK networks in a particular quadrant, as shown in Figure 2–62.

Table 2–27. Global and Regional Clock Connections from Left Side Clock Pins and Fast PLL Outputs (Part 3 of 3)

Left Side Global and Regional Clock Network Connectivity	CLK0	CLK1	CLK2	CLK3	RCLK0	RCLK1	RCLK2	RCLK3	RCLK4	RCLK5	RCLK6	RCLK7
PLL 8 outputs												
c0			✓	✓					✓		✓	
c1			✓	✓						✓		✓
c2	✓	✓							✓		✓	
c3	✓	✓								✓		✓

memory, and transmit this compressed bitstream to Stratix II GX FPGAs. During configuration, the Stratix II GX FPGA decompresses the bitstream in real time and programs its SRAM cells. Stratix II GX FPGAs support decompression in the FPP (when using a MAX II device or microprocessor and flash memory), AS, and PS configuration schemes. Decompression is not supported in the PPA configuration scheme nor in JTAG-based configuration.

Remote System Upgrades

Shortened design cycles, evolving standards, and system deployments in remote locations are difficult challenges faced by system designers. Stratix II GX devices can help effectively deal with these challenges with their inherent re programmability and dedicated circuitry to perform remote system updates. Remote system updates help deliver feature enhancements and bug fixes without costly recalls, reducing time to market, and extending product life.

Stratix II GX FPGAs feature dedicated remote system upgrade circuitry to facilitate remote system updates. Soft logic (Nios processor or user logic) implemented in the Stratix II GX device can download a new configuration image from a remote location, store it in configuration memory, and direct the dedicated remote system upgrade circuitry to initiate a reconfiguration cycle. The dedicated circuitry performs error detection during and after the configuration process, recovers from any error condition by reverting back to a safe configuration image, and provides error status information. This dedicated remote system upgrade circuitry avoids system downtime and is the critical component for successful remote system upgrades.

Remote system configuration is supported in the following Stratix II GX configuration schemes: FPP, AS, PS, and PPA. Remote system configuration can also be implemented in conjunction with Stratix II GX features such as real-time decompression of configuration data and design security using AES for secure and efficient field upgrades.

Refer to the *Remote System Upgrades with Stratix II & Stratix II GX Devices* chapter in volume 2 of the *Stratix II GX Device Handbook* for more information about remote configuration in Stratix II GX devices.

Configuring Stratix II GX FPGAs with JRunner

The JRunner™ software driver configures Altera FPGAs, including Stratix II GX FPGAs, through the ByteBlaster II or ByteBlasterMV cables in JTAG mode. The programming input file supported is in Raw Binary File (**.rbf**) format. JRunner also requires a Chain Description File (**.cdf**)

Table 4–15. Typical Pre-Emphasis (First Post-Tap), Note (1) (Part 2 of 2)

V_{CCH} TX = 1.5 V	First Post Tap Pre-Emphasis Level											
V_{OD} Setting (mV)	1	2	3	4	5	6	7	8	9	10	11	12
600		33%	53%	80%	115%	157%	195%	294%	386%			
900		19%	28%	38%	56%	70%	86%	113%	133%	168%	196%	242%
1200			17%	22%	31%	40%	52%	62%	75%	86%	96%	112%

Note to Table 4–15:
(1) Applicable to data rates from 600 Mbps to 6.375 Gbps. Specification is for measurement at the package ball.

Table 4–16. Typical Pre-Emphasis (First Post-Tap), Note (1)

V_{CCH} TX = 1.2 V	First Post Tap Pre-Emphasis Level											
V_{OD} Setting (mV)	1	2	3	4	5	6	7	8	9	10	11	12
	TX Term = 100 Ω											
320	24%	61%	114%									
480		31%	55%	86%	121%	170%	232%	333%				
640		20%	35%	54%	72%	95%	124%	157%	195%	233%	307%	373%
800			23%	36%	49%	64%	81%	97%	117%	140%	161%	195%
960			18%	25%	35%	44%	57%	69%	82%	94%	108%	127%

Note to Table 4–16:
(1) Applicable to data rates from 600 Mbps to 3.125 Gbps. Specification is for measurement at the package ball.

DC Electrical Characteristics

Table 4–23 shows the Stratix II GX device family DC electrical characteristics.

Table 4–23. Stratix II GX Device DC Operating Conditions (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Device	Minimum	Typical	Maximum	Unit
I_I	Input pin leakage current	$V_I = V_{CCIOmax}$ to 0 V *(2)*	All	–10		10	µA
I_{OZ}	Tri-stated I/O pin leakage current	$V_O = V_{CCIOmax}$ to 0 V *(2)*	All	–10		10	µA
I_{CCINT0}	V_{CCINT} supply current (standby)	V_I = ground, no load, no toggling inputs T_J = 25 °C	EP2SGX30		0.30	*(3)*	A
			EP2SGX60		0.50	*(3)*	A
			EP2SGX90		0.62	*(3)*	A
			EP2SGX130		0.82	*(3)*	A
I_{CCPD0}	V_{CCPD} supply current (standby)	V_I = ground, no load, no toggling inputs T_J = 25 °C, V_{CCPD} = 3.3V	EP2SGX30		2.7	*(3)*	mA
			EP2SGX60		3.6	*(3)*	mA
			EP2SGX90		4.3	*(3)*	mA
			EP2SGX130		5.4	*(3)*	mA
I_{CCIO0}	V_{CCIO} supply current (standby)	V_I = ground, no load, no toggling inputs T_J = 25 °C	EP2SGX30		4.0	*(3)*	mA
			EP2SGX60		4.0	*(3)*	mA
			EP2SGX90		4.0	*(3)*	mA
			EP2SGX130		4.0	*(3)*	mA

Table 4–35. SSTL-18 Class I Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{CCIO}	Output supply voltage		1.71	1.8	1.89	V
V_{REF}	Reference voltage		0.855	0.9	0.945	V
V_{TT}	Termination voltage		V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04	V
V_{IH} (DC)	High-level DC input voltage		V_{REF} + 0.125			V
V_{IL} (DC)	Low-level DC input voltage				V_{REF} – 0.125	V
V_{IH} (AC)	High-level AC input voltage		V_{REF} + 0.25			V
V_{IL} (AC)	Low-level AC input voltage				V_{REF} – 0.25	V
V_{OH}	High-level output voltage	I_{OH} = –6.7 mA *(1)*	V_{TT} + 0.475			V
V_{OL}	Low-level output voltage	I_{OL} = 6.7 mA *(1)*			V_{TT} – 0.475	V

Note to Table 4–35:

(1) This specification is supported across all the programmable drive settings available for this I/O standard as shown in the *Stratix II GX Architecture* chapter in volume 1 of the *Stratix II GX Device Handbook*.

Table 4–36. SSTL-18 Class II Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{CCIO}	Output supply voltage		1.71	1.8	1.89	V
V_{REF}	Reference voltage		0.855	0.9	0.945	V
V_{TT}	Termination voltage		V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04	V
V_{IH} (DC)	High-level DC input voltage		V_{REF} + 0.125			V
V_{IL} (DC)	Low-level DC input voltage				V_{REF} – 0.125	V
V_{IH} (AC)	High-level AC input voltage		V_{REF} + 0.25			V
V_{IL} (AC)	Low-level AC input voltage				V_{REF} – 0.25	V
V_{OH}	High-level output voltage	I_{OH} = –13.4 mA *(1)*	V_{CCIO} – 0.28			V
V_{OL}	Low-level output voltage	I_{OL} = 13.4 mA *(1)*			0.28	V

Note to Table 4–36:

(1) This specification is supported across all the programmable drive settings available for this I/O standard as shown in the *Stratix II GX Architecture* chapter in volume 1 of the *Stratix II GX Device Handbook*.

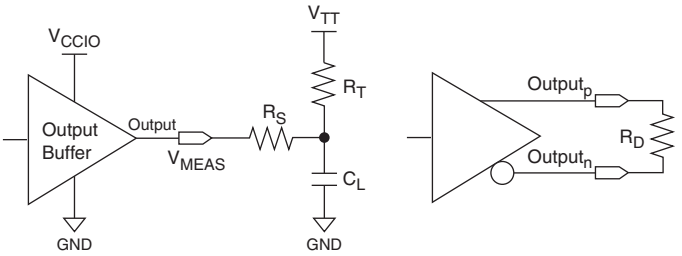
3. Simulate the output driver of choice into the actual PCB trace and load, using the appropriate IBIS model or capacitance value to represent the load.

4. Record the time to V_{MEAS}.

5. Compare the results of steps 2 and 4. The increase or decrease in delay should be added to or subtracted from the I/O Standard Output Adder delays to yield the actual worst-case propagation delay (clock-to-output) of the PCB trace.

The Quartus II software reports the timing with the conditions shown in Table 4–53 using the above equation. Figure 4–8 shows the model of the circuit that is represented by the output timing of the Quartus II software.

Figure 4–8. Output Delay Timing Reporting Setup Modeled by Quartus II



Notes to Figure 4–8:

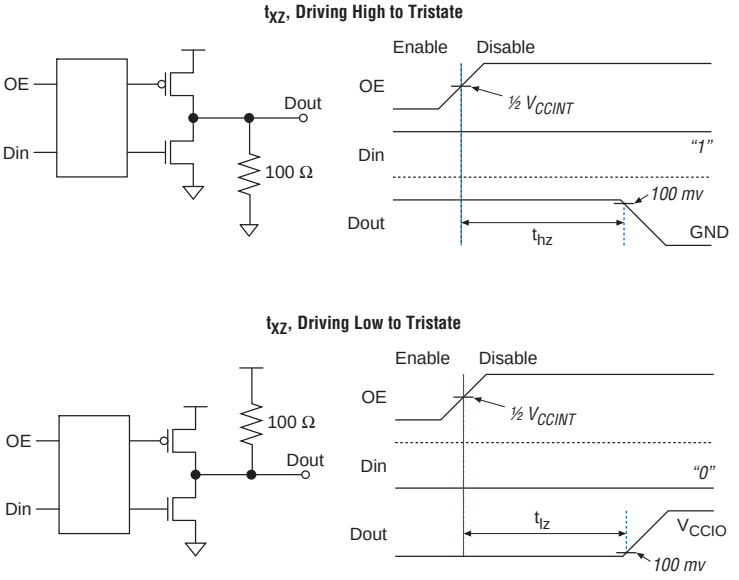
(1) Output pin timing is reported at the output pin of the FPGA device. Additional delays for loading and board trace delay need to be accounted for with IBIS model simulations.
(2) V_{CCPD} is 3.085 V unless otherwise specified.
(3) V_{CCINT} is 1.12 V unless otherwise specified.

Table 4–53. Output Timing Measurement Methodology for Output Pins (Part 1 of 2) *Notes (1), (2), (3)*

I/O Standard	Loading and Termination						Measurement Point
	R_S (Ω)	R_D (Ω)	R_T (Ω)	V_{CCIO} (V)	V_{TT} (V)	C_L (pF)	V_{MEAS} (V)
LVTTL *(4)*				3.135		0	1.5675
LVCMOS *(4)*				3.135		0	1.5675
2.5 V *(4)*				2.375		0	1.1875
1.8 V *(4)*				1.710		0	0.855
1.5 V *(4)*				1.425		0	0.7125

Figures 4–9 and 4–10 show the measurement setup for output disable and output enable timing.

Figure 4–9. Measurement Setup for t_{xz} *Note (1)*



Note to Figure 4–9:

(1) V_{CCINT} is 1.12 V for this measurement.

Table 4–86. Stratix II GX I/O Output Delay for Column Pins (Part 7 of 7)								
I/O Standard	Drive Strength	Parameter	Fast Corner Industrial/ Commercial	-3 Speed Grade (3)	-3 Speed Grade (4)	-4 Speed Grade	-5 Speed Grade	Unit
1.5-V differential HSTL Class I (2)	4 mA	t_{OP}	956	1607	1686	1793	1942	ps
		t_{DIP}	978	1673	1756	1867	2032	ps
	6 mA	t_{OP}	961	1588	1666	1772	1920	ps
		t_{DIP}	983	1654	1736	1846	2010	ps
	8 mA	t_{OP}	943	1590	1668	1774	1922	ps
		t_{DIP}	965	1656	1738	1848	2012	ps
	10 mA	t_{OP}	943	1592	1670	1776	1924	ps
		t_{DIP}	965	1658	1740	1850	2014	ps
	12 mA	t_{OP}	937	1590	1668	1774	1922	ps
		t_{DIP}	959	1656	1738	1848	2012	ps
1.5-V differential HSTL Class II (2)	16 mA	t_{OP}	924	1431	1501	1596	1734	ps
		t_{DIP}	946	1497	1571	1670	1824	ps
	18 mA	t_{OP}	927	1439	1510	1605	1744	ps
		t_{DIP}	949	1505	1580	1679	1834	ps
	20 mA	t_{OP}	929	1450	1521	1618	1757	ps
		t_{DIP}	951	1516	1591	1692	1847	ps

(1) This is the default setting in the Quartus II software.
(2) These I/O standards are only supported on DQS pins.
(3) This column refers to –3 speed grades for EP2SGX30, EP2SGX60, and EP2SGX90 devices.
(4) This column refers to –3 speed grades for EP2SGX130 devices.

Table 4–87. Stratix II GX I/O Output Delay for Row Pins (Part 1 of 4)								
I/O Standard	Drive Strength	Parameter	Fast Corner Industrial/ Commercial	-3 Speed Grade (3)	-3 Speed Grade (4)	-4 Speed Grade	-5 Speed Grade	Unit
LVTTL	4 mA	t_{OP}	1328	2655	2786	2962	3189	ps
		t_{DIP}	1285	2600	2729	2902	3116	ps
	8 mA	t_{OP}	1200	2113	2217	2357	2549	ps
		t_{DIP}	1157	2058	2160	2297	2476	ps
	12 mA (1)	t_{OP}	1144	2081	2184	2321	2512	ps
		t_{DIP}	1101	2026	2127	2261	2439	ps

Table 4–87. Stratix II GX I/O Output Delay for Row Pins (Part 2 of 4)								
I/O Standard	Drive Strength	Parameter	Fast Corner Industrial/ Commercial	-3 Speed Grade (3)	-3 Speed Grade (4)	-4 Speed Grade	-5 Speed Grade	Unit
LVCMOS	4 mA	t_{OP}	1200	2113	2217	2357	2549	ps
		t_{DIP}	1157	2058	2160	2297	2476	ps
	8 mA (1)	t_{OP}	1094	1853	1944	2067	2243	ps
		t_{DIP}	1051	1798	1887	2007	2170	ps
	12 mA (1)	t_{OP}	1061	1723	1808	1922	2089	ps
		t_{DIP}	1018	1668	1751	1862	2016	ps
2.5 V	4 mA	t_{OP}	1183	2091	2194	2332	2523	ps
		t_{DIP}	1140	2036	2137	2272	2450	ps
	8 mA	t_{OP}	1080	1872	1964	2088	2265	ps
		t_{DIP}	1037	1817	1907	2028	2192	ps
	12 mA (1)	t_{OP}	1061	1775	1862	1980	2151	ps
		t_{DIP}	1018	1720	1805	1920	2078	ps
1.8 V	2 mA	t_{OP}	1253	2954	3100	3296	3542	ps
		t_{DIP}	1210	2899	3043	3236	3469	ps
	4 mA	t_{OP}	1242	2294	2407	2559	2763	ps
		t_{DIP}	1199	2239	2350	2499	2690	ps
	6 mA	t_{OP}	1131	2039	2140	2274	2462	ps
		t_{DIP}	1088	1984	2083	2214	2389	ps
	8 mA (1)	t_{OP}	1100	1942	2038	2166	2348	ps
		t_{DIP}	1057	1887	1981	2106	2275	ps
1.5 V	2 mA	t_{OP}	1213	2530	2655	2823	3041	ps
		t_{DIP}	1170	2475	2598	2763	2968	ps
	4 mA (1)	t_{OP}	1106	2020	2120	2253	2440	ps
		t_{DIP}	1063	1965	2063	2193	2367	ps
SSTL-2 Class I	8 mA	t_{OP}	1050	1759	1846	1962	2104	ps
		t_{DIP}	1007	1704	1789	1902	2031	ps
	12 mA (1)	t_{OP}	1026	1694	1777	1889	2028	ps
		t_{DIP}	983	1639	1720	1829	1955	ps
SSTL-2 Class II	16 mA (1)	t_{OP}	992	1581	1659	1763	1897	ps
		t_{DIP}	949	1526	1602	1703	1824	ps

Table 4–91. Stratix II GX Maximum Output Clock Rate for Column Pins (Part 2 of 3)					
I/O Standard	**Drive Strength**	**-3 Speed Grade**	**-4 Speed Grade**	**-5 Speed Grade**	**Unit**
SSTL-18 Class I	4 mA	200	150	150	MHz
	6 mA	350	250	200	MHz
	8 mA	450	300	300	MHz
	10 mA	500	400	400	MHz
	12 mA *(1)*	700	550	400	MHz
SSTL-18 Class II	8 mA	200	200	150	MHz
	16 mA	400	350	350	MHz
	18 mA	450	400	400	MHz
	20 mA *(1)*	550	500	450	MHz
1.8-V HSTL Class I	4 mA	300	300	300	MHz
	6 mA	500	450	450	MHz
	8 mA	650	600	600	MHz
	10 mA	700	650	600	MHz
	12 mA *(1)*	700	700	650	MHz
1.8-V HSTL Class II	16 mA	500	500	450	MHz
	18 mA	550	500	500	MHz
	20 mA *(1)*	650	550	550	MHz
1.5-V HSTL Class I	4 mA	350	300	300	MHz
	6 mA	500	500	450	MHz
	8 mA	700	650	600	MHz
	10 mA	700	700	650	MHz
	12 mA *(1)*	700	700	700	MHz
1.5-V HSTL Class II	16 mA	600	600	550	MHz
	18 mA	650	600	600	MHz
	20 mA *(1)*	700	650	600	MHz
PCI	-	1000	790	670	MHz
PCI-X	-	1000	790	670	MHz
Differential SSTL-2 Class I	8 mA	400	300	300	MHz
	12 mA	400	400	350	MHz
Differential SSTL-2 Class II	16 mA	350	350	300	MHz
	20 mA	400	350	350	MHz
	24 mA	400	400	350	MHz

Table 4–95. Stratix II GX Maximum Output Clock Rate for Row Pins (Series Termination) (Part 2 of 2)					
I/O Standard	**Drive Strength**	**-3 Speed Grade**	**-4 Speed Grade**	**-5 Speed Grade**	**Unit**
SSTL-2 Class I	OCT_50_OHMS	600	500	500	MHz
SSTL-2 Class II	OCT_25_OHMS	600	550	500	MHz
SSTL-18 Class I	OCT_50_OHMS	590	400	350	MHz
1.5-V HSTL Class I	OCT_50_OHMS	600	550	500	MHz
1.8-V HSTL Class I	OCT_50_OHMS	650	600	600	MHz
Differential SSTL-2 Class I	OCT_50_OHMS	600	500	500	MHz
Differential SSTL-2 Class II	OCT_25_OHMS	600	550	500	MHz
Differential SSTL-18 Class I	OCT_50_OHMS	590	400	350	MHz
Differential HSTL-18 Class I	OCT_50_OHMS	650	600	600	MHz
Differential HSTL-15 Class I	OCT_50_OHMS	600	550	500	

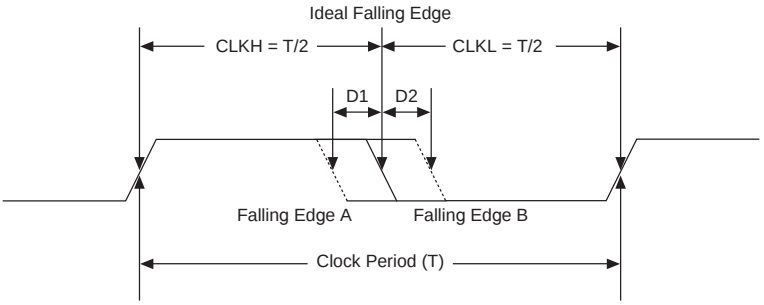
Table 4–96 shows the maximum output clock toggle rate for Stratix II GX device series-terminated dedicated clock pins.

Table 4–96. Stratix II GX Maximum Output Clock Rate for Dedicated Clock Pins (Series Termination) (Part 1 of 2)					
I/O Standard	**Drive Strength**	**-3 Speed Grade**	**-4 Speed Grade**	**-5 Speed Grade**	**Unit**
LVTTL	OCT_25_OHMS	400	400	350	MHz
	OCT_50_OHMS	400	400	350	MHz
LVCMOS	OCT_25_OHMS	350	350	300	MHz
	OCT_50_OHMS	350	350	300	MHz
2.5 V	OCT_25_OHMS	350	350	300	MHz
	OCT_50_OHMS	350	350	300	MHz
1.8 V	OCT_25_OHMS	700	550	450	MHz
	OCT_50_OHMS	700	550	450	MHz
1.5 V	OCT_50_OHMS	550	450	400	MHz
SSTL-2 Class I	OCT_50_OHMS	600	500	500	MHz
SSTL-2 Class II	OCT_25_OHMS	600	550	500	MHz
SSTL-18 Class I	OCT_50_OHMS	450	400	350	MHz

Duty Cycle Distortion

Duty cycle distortion (DCD) describes how much the falling edge of a clock is off from its ideal position. The ideal position is when both the clock high time (CLKH) and the clock low time (CLKL) equal half of the clock period (T), as shown in Figure 4–11. DCD is the deviation of the non-ideal falling edge from the ideal falling edge, such as D1 for the falling edge A and D2 for the falling edge B (see Figure 4–11). The maximum DCD for a clock is the larger value of D1 and D2.

Figure 4–11. Duty Cycle Distortion



DCD expressed in absolution derivation, for example, D1 or D2 in Figure 4–11, is clock-period independent. DCD can also be expressed as a percentage, and the percentage number is clock-period dependent. DCD as a percentage is defined as:

(T/2 – D1) / T (the low percentage boundary)

(T/2 + D2) / T (the high percentage boundary)

DCD Measurement Techniques

DCD is measured at an FPGA output pin driven by registers inside the corresponding I/O element (IOE) block. When the output is a single data rate signal (non-DDIO), only one edge of the register input clock (positive or negative) triggers output transitions (Figure 4–12). Therefore, any DCD present on the input clock signal or caused by the clock input buffer or different input I/O standard does not transfer to the output signal.

Figure 4–14. Stratix II GX JTAG Waveforms.

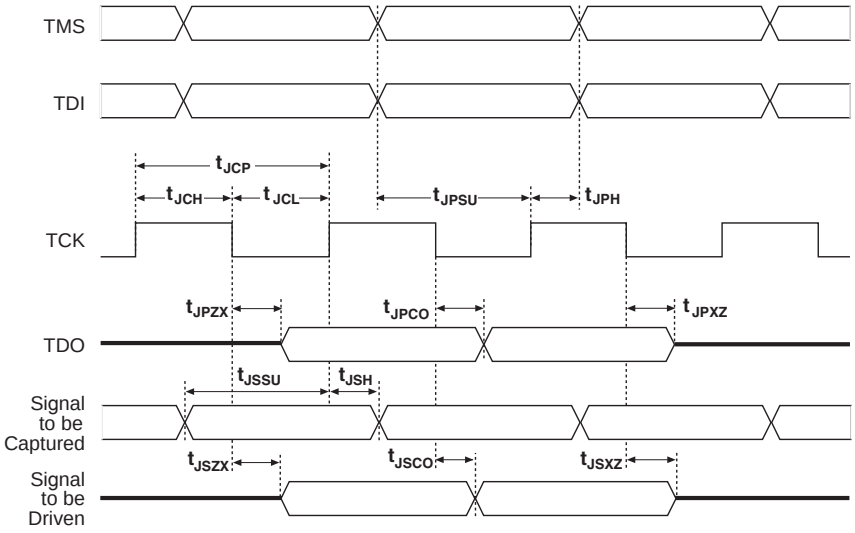


Table 4–117 shows the JTAG timing parameters and values for Stratix II GX devices.

Table 4–117. Stratix II GX JTAG Timing Parameters and Values

Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	30		ns
t_{JCH}	TCK clock high time	12		ns
t_{JCL}	TCK clock low time	12		ns
t_{JPSU}	JTAG port setup time	4		ns
t_{JPH}	JTAG port hold time	5		ns
t_{JPCO}	JTAG port clock to output		9	ns
t_{JPZX}	JTAG port high impedance to valid output		9	ns
t_{JPXZ}	JTAG port valid output to high impedance		9	ns
t_{JSSU}	Capture register setup time	4		ns
t_{JSH}	Capture register hold time	5		ns
t_{JSCO}	Update register clock to output		12	ns
t_{JSZX}	Update register high impedance to valid output		12	ns
t_{JSXZ}	Update register valid output to high impedance		12	ns